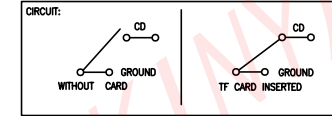


* 所有原料材质, 生产制程, 电镀必须符合H要求

NO.	ASSIGNMENT	NO.	ASSIGNMENT
1#	DAT2	5#	CLK
2#	CD/DAT3 ²	6#	VSS
3#	CMD	7#	DAT0
4#	VDD	8#	DAT1



NOTE:

1. Material:

1-1 Housing: High Temperature Thermoplastic, (LCP MG350) Color Black UL 94V-0

1-2 Contact: Copper Alloy (C5191-EH, T=0.15±0.03mm)

1-3 Cover: Stainless Steel (SUS304-3/4H T=0.15±0.03mm)

2. Plating:

2-1 Contact terminal:

Contact area: Gold 0.5u" Min.

Solder area: Sn overall 80u" Min.

Underplating: Ni overall 30u" Min.

2-2 Cover:

Solder area: Gold 0.5u" Min.

Underplating: Ni overall 30u" Min.

3. Specification:

3-1. Current Rating :0.5A AC/DC max.

3-2. Voltage Rating :12V AC/DC

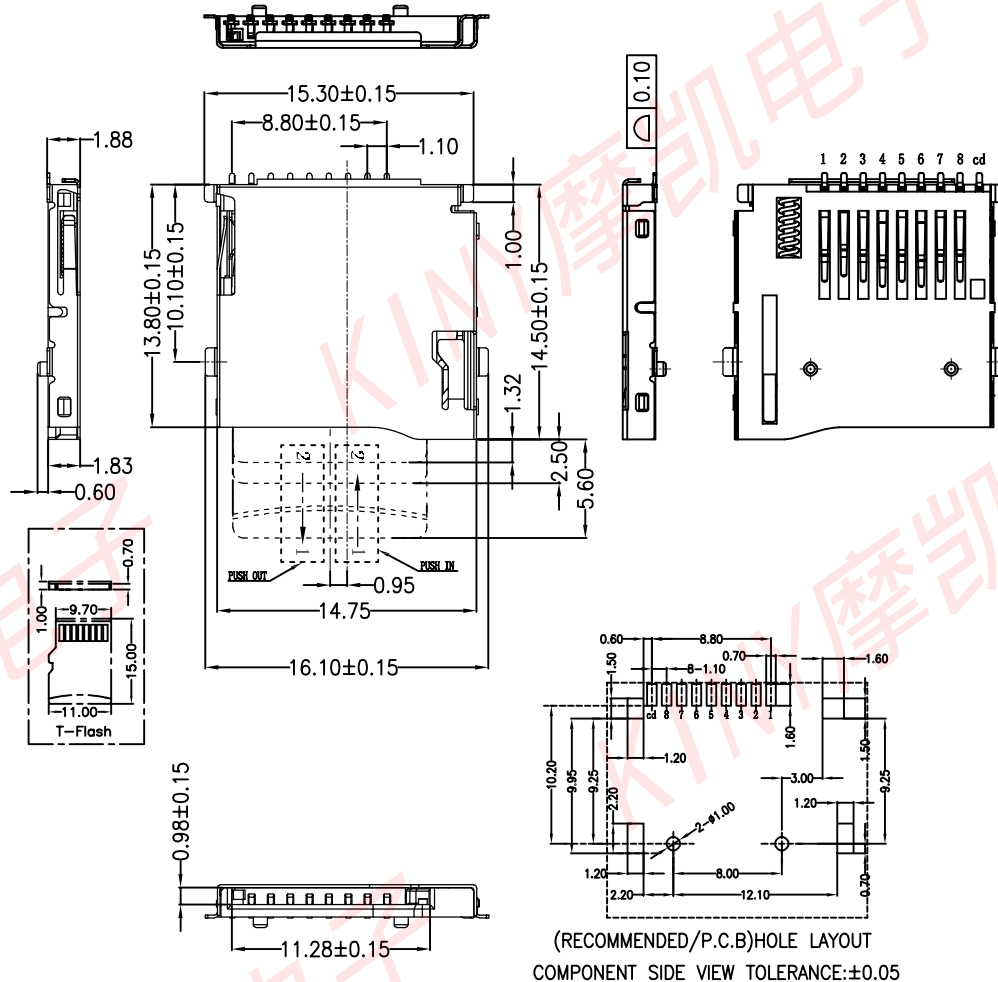
3-3. Ambient Temperature Range : -25°C ~ +85°C

3-4. Ambient Humidity Range :95% R.H. Max.

3-5. Contact Resistance: 100mΩ max.

3-6. Insulation Resistance: 1000MΩ min./500VDC

3-7. Durability: 5,000 cycles



KINNY		东莞市摩凯电子有限公司							
DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NAME :	Micro SD外焊9 PIN H=1.85mm	DRAWING:	Janyz	DATE:	2019.07.18			
	PRODUCT NO. :	TF185-T1231-11-W	CHECK:	Alex	DATE:	2019.07.18			
	DRAWING NO. :	D-TF185-T1231-11-W	APPROVED:	Alex	DATE:	2019.07.18			
			SCALE:	1:1	DWG ID:	C D	REV.:	A	PAGE:

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
A	---	NEW RELEASE	janyz	2019.07.18
1				